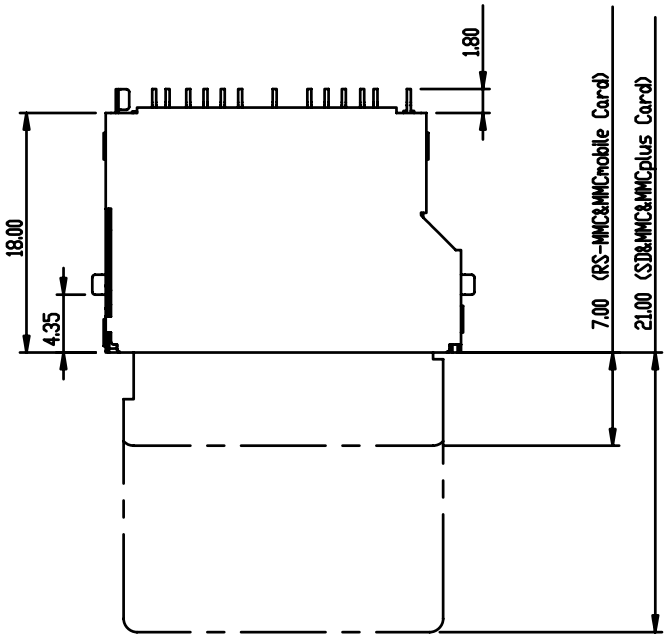



NOTES :

1. MATERIAL :

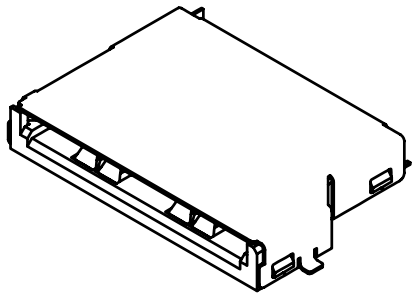
INSULATOR : HIGH TEMPERATURE THERMOPLASTIC , UL94V-0. COLOR : BLACK

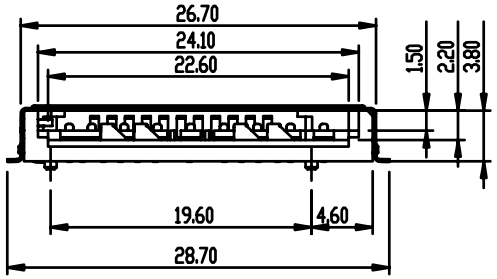
CONTACT : PHOSPHOR BRONZE.

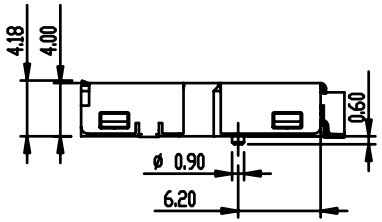
PLATING :

CONTACT AREA :GOLD FLASH,10u" Au Plated OVER Ni

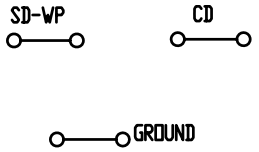
SOLDER AREA : Tin Plated OVER Ni



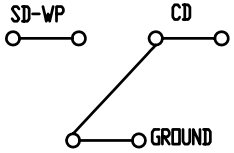


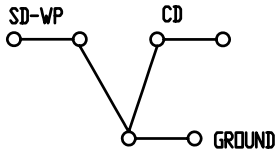

CIRCUIT




WITHOUT CARD



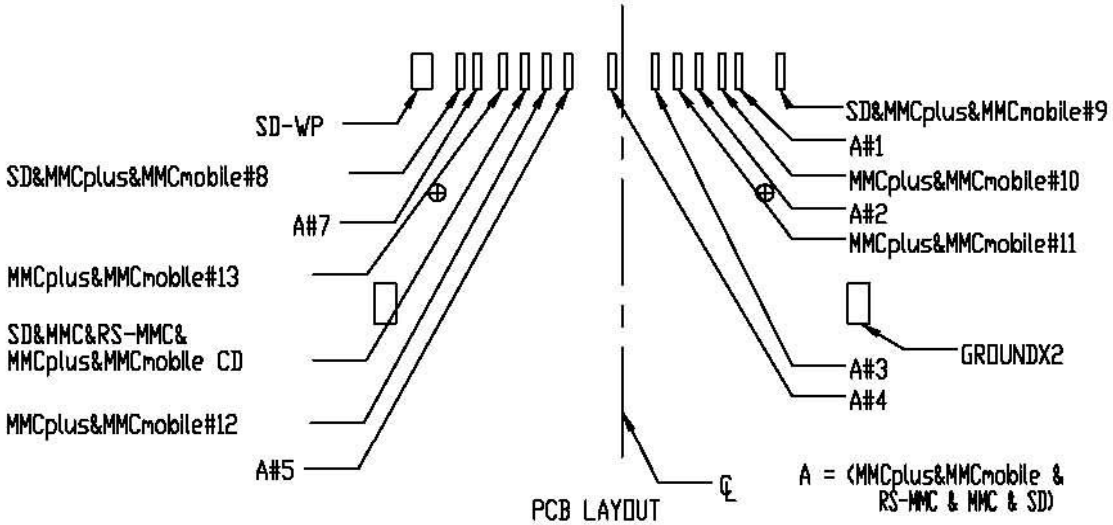

SD CARD INSERTED
WRITE PROTECT : LOCK




SD CARD INSERTED
1.WRITE PROTECT :UNLOCK
2.OTHET CARD INSERTED

| | | | |
|---|---|---|---|
| UNLESS OTHERWISE SPECIFIED TOLERANCE<br>ANG. ±5°<br>0. ±0.3<br>.0 ±0.25<br>.00 ±0.20 | | | 豪國興業股份有限公司 |
| SCALE: AS SHOWED | UNIT: mm | | |
| DRAWN | 2008/8/5 | | DRAWN NAME: Multi Card 5 in 1 Socket SD/MMC/RS MMC/MMC Plus(4.0)/MMC Mobile(4.0) |
| CHECKED | / / | | |
| APPROVED | / / | | PRODUCT NO. SDMMC4009RS |
| SIZE A4 | REV. | | FILE NAME: |

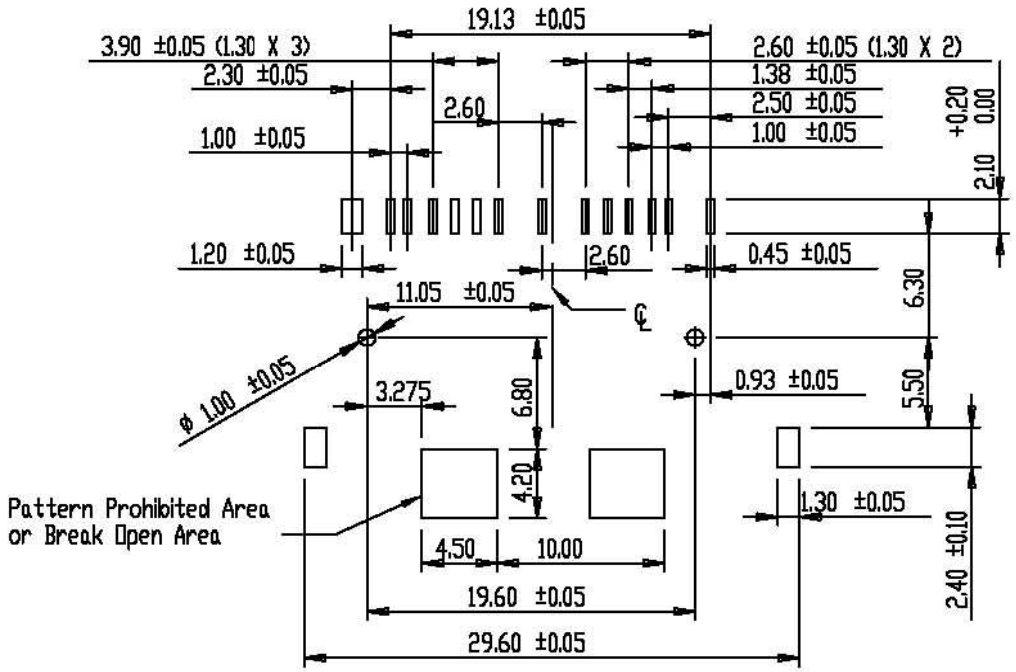
| REV. | DESCRIPTION | DATE |
|---|---|---|
| | | |




PCB LAYOUT

## PIN ASSIGNMENT

| | |
|---|---|
| MMCplus&MMCmobile&MMC&RS-MMC&SD#1 | (RSV/DAT3) |
| MMCplus&MMCmobile&MMC&RS-MMC&SD#2 | (CMD) |
| MMCplus&MMCmobile&MMC&RS-MMC&SD#3 | (GND) |
| MMCplus&MMCmobile&MMC&RS-MMC&SD#4 | (VCC) |
| MMCplus&MMCmobile&MMC&RS-MMC&SD#5 | (CLK) |
| MMCplus&MMCmobile&MMC&RS-MMC&SD#7 | (DAT0) |
| MMCplus&MMCmobile&SD#8 | (DAT1) |
| MMCplus&MMCmobile&SD#9 | (DAT2) |
| MMCplus&MMCmobile#10 | (DAT4) |
| MMCplus&MMCmobile#11 | (DAT5) |
| MMCplus&MMCmobile#12 | (DAT6) |
| MMCplus&MMCmobile#13 | (DAT7) |




PCB LAYOUT

UNLESS OTHERWISE SPECIFIED TOLERANCE
ANG. ±5'
0. ±0.3
.0 ±0.25
.00 ±0.20

豪國興業股份有限公司

| | | | |
|---|---|---|---|
| SCALE: AS SHOWED | UNIT: mm | | |
| DRAWN | 2007/1/10 | DRAWN NAME: Multi Card 5 in 1 Socket SD/MMC/RS MMC/MMC Plus(4.0)/MMC Mobile(4.0) | |
| CHECKED | / / | | |
| APPROVED | / / | PRODUCT NO. SDMMC4009RS-2 | |
| SIZE A4 | REV. | FILE NAME: | |

| REV. | DESCRIPTION | DATE |
|---|---|---|
| | | |